

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S86	292	etch\$4 same ((xanthan or cellulose or ethylcellulose or gum or alkyl adj methacrylates or hydroxyalkylguar) and (alkaline or basic or anisotropic or hydroxide or caustic or NaOH or KOH or ammonia or ethanolamine or ethylenediamine)) and (silicon or wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 10:39
S87	385	((xanthan or cellulose or ethylcellulose or gum or alkyl adj methacrylates or hydroxyalkylguar) same (alkaline or basic or anisotropic or hydroxide or caustic or NaOH or KOH or ammonia or ethanolamine or ethylenediamine)) and (silicon or wafer) same etch\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 10:40
S88	44	((xanthan or cellulose or ethylcellulose or gum or alkyl adj methacrylates or hydroxyalkylguar) same (alkaline or basic or anisotropic or hydroxide or caustic or NaOH or KOH or ammonia or ethanolamine or ethylenediamine)) and (silicon or wafer) same etch\$4 and (ink adj jet or printable or jettable or jetable)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 10:41
S89	25	(szlufcik).in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 10:48
S90	21	"5296043"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 10:58
S91	30	(naoh or koh or (hydroxide near (sodium or potassium))) same (water or popylene adj carbonate or carboxylic adj acid adj ester or h2o or "h.sub.2o") same (thickener or xanthan or cellulose or carboxymethylcellulose or carboxymethylhydroxyethylcellulose or paste) and etch\$4 near2 (paste or thicken or thick or thickening)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 11:43
S92	2	"20020034611"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 12:30
S93	5	"6524880"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 12:32
S94	2	"20020153039"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 12:33

S95	3	"2002016221"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 12:41
S96	2	"20020016221"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 12:41
S98	2	"20020162218"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 12:43
S99	255	(NaOH or KOH) same ("30" or "31" or "32" or "33" or "34" or "35" or "36" or "37" or "38" or "39" or "40" or "45" or "50" or "55" or "60") same (weight or wt) and etch\$4 and (silicon or "sio. sub.2" or sio2 or silicon adj dioxide) and paste	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 13:06
S100	52	(NaOH or KOH) same ("30" or "31" or "32" or "33" or "34" or "35" or "36" or "37" or "38" or "39" or "40" or "45" or "50" or "55" or "60") same (weight or wt) and etch\$4 and (silicon or "sio. sub.2" or sio2 or silicon adj dioxide) and paste same etch\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 13:07
S101	25	"6641948"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/08 07:39
S104	104	(propylene adj carbonate same (water or "h. sub.2o" or h2o)) same (solubility or dissolv\$4) same (hydroxide or koh or naoh)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/08 10:01
S105	34	(propylene adj carbonate) with (solubility or dissolv\$4 or soluble) with (hydroxide or koh or naoh)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/08 10:13
S109	5	(butoxy adj ethoxy adj ethyl adj acetate or butoxyethoxyethyl adj acetate or "butoxy(ethoxy ethyl)" with (hydroxide or koh or naoh)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/08 10:21
S112	93	hotplate with "80"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/08 10:30

S113	1280	hotplate same (silicon or wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/08 10:30
S114	144	hotplate same (silicon or wafer) same etch\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/08 10:30
S115	30	hotplate same (silicon or wafer) same etch\$4 and (chemical or aqueous or fluid or liquid or paste) near3 etch\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/08 10:32
S117	1	01/83391	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/08 10:41
S118	0	2001/83391	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/08 10:41
S119	2	"200183391"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/08 10:41
S122	2	(IR or infrared or infra adj red) adj lamp with heat same (NaoH or KOH) same etch\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/08 11:14
S123	4	(IR or infrared or infra adj red) with heat same (NaoH or KOH) same etch\$4 and (chemical or aqueous or fluid or liquid or paste) near3 etch\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/08 11:15
S124	1	(IR or infrared or infra adj red) with heat with activated same etch\$4 and (chemical or aqueous or fluid or liquid or paste) near3 etch\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/08 11:16
S125	549	(propylene adj carbonate) with water and propylene adj carbonate with (improv\$4 or better or superior or more or less or greater or faster or slower or facilitat\$4 or enabl\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/08 11:42

S126	5	(propylene adj carbonate) with (hydroxide or koh or naoh) and etch\$4 with (hydroxide or koh or naoh)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/08 11:50
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